


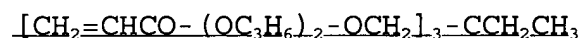
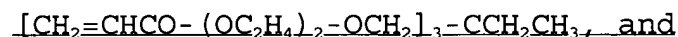
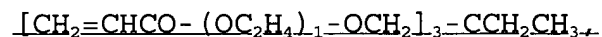
$$\begin{array}{c} \text{H}_2\text{C}=\overset{\text{R}}{\underset{|}{\text{C}}}-\overset{\text{O}}{\parallel}\text{C}-\text{O}-\overset{\text{H}_2}{\underset{|}{\text{C}}}-\text{HC}-\text{H}_2\text{C}-\text{A}-\text{CH}_2-\text{CH}-\overset{\text{H}_2}{\underset{|}{\text{C}}}-\overset{\text{O}}{\parallel}\text{C}-\overset{\text{R}}{\underset{|}{\text{C}}}=\text{CH}_2 \\ | \qquad \qquad \qquad | \qquad \qquad \qquad | \\ -\text{O} \qquad \qquad \qquad \text{OOC}-\text{Y}-\text{CO}- \\ | \\ n(\text{HOOC}) \end{array} \quad (1)$$

Chemical structure (2) is a biphenyl derivative. It consists of two benzene rings connected by a central group X . The left benzene ring has a substituent R_1 at the top position, a substituent R_2 at the bottom position, and an oxygen atom (O) at the left position, which is connected to a horizontal line. The right benzene ring has a substituent R_1 at the top position, a substituent R_2 at the bottom position, and an oxygen atom (O) at the right position, which is connected to a horizontal line. The central group X is positioned between the two rings.



(3)

b) 10-100 parts by weight of (B) which is at least one acrylate selected from ~~(meth)acrylates or oligomers thereof, wherein said at least one acrylate is modified with ethylene oxide or propylene oxide, and wherein said at least one acrylate is selected from the group consisting of:~~



~~hydroxyethyl (meth)acrylate, hydroxypropyl (meth)acrylate, 2-hydroxyethylhexyl (meth)acrylate, polyethylene glycol mono(meth)acrylate, polypropylene glycol mono(meth)acrylate, butanediol mono(meth)acrylate, chlorohydroxypropyl (meth)acrylate, allyl (meth)acrylate, butoxyethyl (meth)acrylate, triethylene glycol butyl ether (meth)acrylate, t-butylaminoethyl (meth)acrylate, caprolactone (meth)acrylate, butyl (meth)acrylate, hexyl (meth)acrylate, cyanoethyl (meth)acrylate, dimethylaminoethyl (meth)acrylate, diethylamino (meth)acrylate, ethoxyethyl (meth)acrylate, ethylhexyl (meth)acrylate, isodecyl (meth)acrylate, isooctyl (meth)acrylate, lauryl (meth)acrylate, octyl (meth)acrylate, stearyl (meth)acrylate, succinic acid (meth)acrylate, methacryloyloxypropyl-trimethoxysilane, methoxyethyl (meth)acrylate, cyclodecatrienyl (meth)acrylate, glycerol (meth)acrylate, glycidyl (meth)acrylate, isocyanatoethyl~~

~~(meth)acrylate, heptadecafluorooctyl (meth)acrylate, octafluoropentyl (meth)acrylate, tetrafluoropropyl (meth)acrylate, trifluoroethyl (meth)acrylate, dibromopropyl (meth)acrylate, cyclohexyl (meth)acrylate, dicyclopentanyl (meth)acrylate, dicyclopentenyl (meth)acrylate, isobornyl (meth)acrylate, tetrahydrofurfuryl (meth)acrylate, morpholino (meth)acrylate, phenoxyethyl (meth)acrylate, phenoxyhydroxypropyl (meth)acrylate, polypropylene glycol nonylphenyl ether (meth)acrylate, phenyl (meth)acrylate, phthalic acid (meth)acrylate, benzyl (meth)acrylate, phenoxyated phosphoric acid (meth)acrylate, phosphoric acid (meth)acrylate, butoxyated phosphoric acid (meth)acrylate, octoxyated phosphoric acid (meth)acrylate, sodium sulfonate (meth)acrylate, ethylene glycol di(meth)acrylate, diethylene glycol di(meth)acrylate, hexanediol di(meth)acrylate, di(meth)acrylates of long-chain aliphatic diols, neopentyl glycol di(meth)acrylate, hydroxypivalic acid neopentyl glycol di(meth)acrylate, stearic acid-modified pentaerythritol di(meth)acrylate, propylene glycol di(meth)acrylate, glycerol di(meth)acrylate, triethylene glycol di(meth)acrylate, tetraethylene glycol di(meth)acrylate, triethylene glycol divinyl ether, tetramethylene glycol di(meth)acrylate, butylene glycol di(meth)acrylate, dicyclopentanyl di(meth)acrylate, polyethylene glycol di(meth)acrylate, polypropylene glycol~~

~~di(meth)acrylate, triglycerol di(meth)acrylate, neopentyl glycol-modified trimethylolpropane di(meth)acrylate, allylated cyclohexyl di(meth)acrylate, methoxylated cyclohexyl di(meth)acrylate, acrylic group-substituted isocyanurate, bis(acryloyloxyneopentyl) adipate, bisphenol A di(meth)acrylate, bisphenol S di(meth)acrylate, butanediol di(meth)acrylate, phthalic acid di(meth)acrylate, phosphoric acid di(meth)acrylate, zinc di(meth)acrylate, trimethylolpropane tri(meth)acrylate, trimethylolethane tri(meth)acrylate, glycerol tri(meth)acrylate, pentaerythritol tri(meth)acrylate, alkyl-modified dipentaerythritol tri(meth)acrylate, phosphoric acid tri(meth)acrylate, tris((meth)acryloyloxyethyl) isocyanurate, pentaerythritol tetra(meth)acrylate, dipentaerythritol tetra(meth)acrylate, ditrimethylol-propane tetraacrylate, alkyl-modified dipentaerythritol tetra(meth)acrylate, dipentaerythritol penta(meth)acrylate, dipentaerythritol hexa(meth)acrylate, alkyl-modified dipentaerythritol penta(meth)acrylate, urethane tri(meth)acrylate, ester tri(meth)acrylate, urethane hexa(meth)acrylate, and ester hexa(meth)acrylate;~~

c) 0-50 10-40 parts by weight of (C) compound containing epoxy group and

d) 0-10 parts by weight of (D) photopolymerization initiator or sensitizer.

2. (Original) A photo- or heat-curable resin composition as described in claim 1 wherein at least a part of the unsaturated compound (A) is an unsaturated compound having the fluorene skeleton represented by the formula (3) in its structural unit.

3. (Original) A photo- or heat-curable resin composition as described in claim 1 wherein at least one kind of other unsaturated compound (E) selected from other monomers and oligomers is incorporated at a rate of 100 parts or less per 100 parts by weight of the component A in addition to the components A, B, C and D.

4. (Withdrawn) A printed wiring board wherein a resin insulation layer is formed by the cured product of a photo- or heat-curable resin composition as described in claim 1.

5. (Withdrawn) A cured resin formed by curing a photo- or heat-curable resin composition as described in claim 1.

6. (Cancelled)